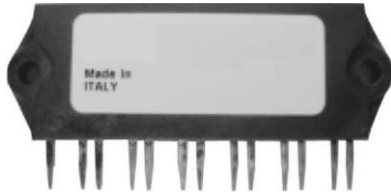


## IGBT SIP Module (Short Circuit Rated Ultrafast IGBT)


**IMS-2**

<b>PRODUCT SUMMARY</b>	
<b>OUTPUT CURRENT IN A TYPICAL 20 kHz MOTOR DRIVE</b>	
$I_{RMS}$ per phase (3.1 kW total) with $T_C = 90\text{ }^\circ\text{C}$	11 $A_{RMS}$
$T_J$	125 $^\circ\text{C}$
Supply voltage	360 Vdc
Power factor	0.8
Modulation depth (see fig. 1)	115 %
$V_{CE(on)}$ (typical) at $I_C = 13\text{ A}$ , 25 $^\circ\text{C}$	1.8 V

**FEATURES**

- Short circuit rated ultrafast: Optimized for high speed > 5.0 kHz, and short circuit rated to 10  $\mu\text{s}$  at 125  $^\circ\text{C}$ ,  $V_{GE} = 15\text{ V}$
- Fully isolated printed circuit board mount package
- Switching-loss rating includes all “tail” losses
- HEXFRED<sup>®</sup> soft ultrafast diodes
- Totally lead (Pb)-free and RoHS compliant
- Designed and qualified for industrial level


**RoHS  
COMPLIANT**
**DESCRIPTION**

The IGBT technology is the key to Vishay’s HPP advanced line of IMS (Insulated Metal Substrate) power modules. These modules are more efficient than comparable bipolar transistor modules, while at the same time having the simpler gate-drive requirements of the familiar power MOSFET. This superior technology has now been coupled to a state of the art materials system that maximizes power throughput with low thermal resistance. This package is highly suited to motor drive applications and where space is at a premium.

<b>ABSOLUTE MAXIMUM RATINGS</b>				
PARAMETER	SYMBOL	TEST CONDITIONS	MAX.	UNITS
Collector to emitter voltage	$V_{CES}$		600	V
Continuous collector current	$I_C$	$T_C = 25\text{ }^\circ\text{C}$	24	A
		$T_C = 100\text{ }^\circ\text{C}$	13	
Pulsed collector current	$I_{CM}^{(1)}$		48	
Clamped inductive load current	$I_{LM}^{(2)}$		48	
Short circuit withstand time	$t_{SC}$	$T_C = 100\text{ }^\circ\text{C}$	9.3	$\mu\text{s}$
Gate to emitter voltage	$V_{GE}$		$\pm 20$	V
Isolation voltage	$V_{ISOL}$	$t = 1\text{ min}$ , any terminal to case	2500	$V_{RMS}$
Maximum power dissipation, each IGBT	$P_D$	$T_C = 25\text{ }^\circ\text{C}$	63	W
		$T_C = 100\text{ }^\circ\text{C}$	25	
Operating junction and storage temperature range	$T_J, T_{Stg}$		- 55 to + 150	$^\circ\text{C}$
Soldering temperature		For 10 s, (0.063" (1.6 mm) from case)	300	
Mounting torque		6-32 or M3 screw	5 to 7 (0.55 to 0.8)	

**Notes**

(1) Repetitive rating;  $V_{GE} = 20\text{ V}$ , pulse width limited by maximum junction temperature (see fig. 20)

(2)  $V_{CC} = 80\%$  ( $V_{CES}$ ),  $V_{GE} = 20\text{ V}$ ,  $L = 10\text{ }\mu\text{H}$ ,  $R_G = 10\text{ }\Omega$  (see fig. 19)

THERMAL AND MECHANICAL SPECIFICATIONS				
PARAMETER	SYMBOL	TYP.	MAX.	UNITS
Junction to case, each IGBT, one IGBT in conduction	$R_{thJC}$ (IGBT)	-	2.2	°C/W
Junction to case, each DIODE, one DIODE in conduction	$R_{thJC}$ (DIODE)	-	3.7	
Case to sink, flat, greased surface	$R_{thCS}$ (MODULE)	0.10	-	
Weight of module		20	-	g
		0.7	-	oz.

ELECTRICAL SPECIFICATIONS ( $T_J = 25\text{ }^\circ\text{C}$ unless otherwise specified)							
PARAMETER	SYMBOL	TEST CONDITIONS		MIN.	TYP.	MAX.	UNITS
Collector to emitter breakdown voltage	$V_{(BR)CES}^{(1)}$	$V_{GE} = 0\text{ V}, I_C = 250\text{ }\mu\text{A}$		600	-	-	V
Temperature coeff. of breakdown voltage	$\Delta V_{(BR)CES}/\Delta T_J$	$V_{GE} = 0\text{ V}, I_C = 1.0\text{ mA}$		-	0.63	-	V/°C
Collector to emitter saturation voltage	$V_{CE(on)}$	$I_C = 13\text{ A}$	$V_{GE} = 15\text{ V}$ See fig. 2, 5	-	1.80	2.3	V
		$I_C = 24\text{ A}$		-	1.80	-	
		$I_C = 13\text{ A}, T_J = 150\text{ }^\circ\text{C}$		-	1.56	1.73	
Gate threshold voltage	$V_{GE(th)}$	$V_{CE} = V_{GE}, I_C = 250\text{ }\mu\text{A}$		3.0	-	6.0	mV/°C
Temperature coeff. of threshold voltage	$\Delta V_{GE(th)}/\Delta T_J$			-	-13	-	
Forward transconductance	$g_{fe}^{(2)}$	$V_{CE} = 100\text{ V}, I_C = 10\text{ A}$		11	18	-	S
Zero gate voltage collector current	$I_{CES}$	$V_{GE} = 0\text{ V}, V_{CE} = 600\text{ V}$		-	-	250	$\mu\text{A}$
		$V_{GE} = 0\text{ V}, V_{CE} = 600\text{ V}, T_J = 150\text{ }^\circ\text{C}$		-	-	3500	
Diode forward voltage drop	$V_{FM}$	$I_C = 15\text{ A}$	See fig. 13	-	1.3	1.7	V
		$I_C = 15\text{ A}, T_J = 150\text{ }^\circ\text{C}$		-	1.2	1.6	
Gate to emitter leakage current	$I_{GES}$	$V_{GE} = \pm 20\text{ V}$		-	-	$\pm 100$	nA

**Notes**

(1) Pulse width  $\leq 80\text{ }\mu\text{s}$ , duty factor  $\leq 0.1\%$

(2) Pulse width  $5.0\text{ }\mu\text{s}$ ; single shot



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SWITCHING CHARACTERISTICS (T <sub>J</sub> = 25 °C unless otherwise specified)								
PARAMETER	SYMBOL	TEST CONDITIONS		MIN.	TYP.	MAX.	UNITS	
Total gate charge (turn-on)	Q <sub>g</sub>	I <sub>C</sub> = 13 A		-	110	170	nC	
Gate to emitter charge (turn-on)	Q <sub>ge</sub>	V <sub>CC</sub> = 400 V		-	14	21		
Gate to collector charge (turn-on)	Q <sub>gc</sub>	V <sub>GE</sub> = 15 V See fig. 8		-	49	74		
Turn-on delay time	t <sub>d(on)</sub>	T <sub>J</sub> = 25 °C I <sub>C</sub> = 13 A, V <sub>CC</sub> = 480 V V <sub>GE</sub> = 15 V, R <sub>G</sub> = 10 Ω Energy losses include "tail" and diode reverse recovery See fig. 9, 10, 18		-	50	-	ns	
Rise time	t <sub>r</sub>			-	30	-		
Turn-off delay time	t <sub>d(off)</sub>			-	110	170		
Fall time	t <sub>f</sub>			-	91	140		
Turn-on switching loss	E <sub>on</sub>			-	0.56	-		mJ
Turn-off switching loss	E <sub>off</sub>	-	0.28	-				
Total switching loss	E <sub>ts</sub>	-	0.84	1.1				
Short circuit withstand time	t <sub>sc</sub>	V <sub>CC</sub> = 360 V, T <sub>J</sub> = 125 °C V <sub>GE</sub> = 15 V, R <sub>G</sub> = 10 Ω, V <sub>CPK</sub> < 500 V		10	-	-	μs	
Turn-on delay time	t <sub>d(on)</sub>	T <sub>J</sub> = 150 °C, see fig. 9, 10, 11, 18 I <sub>C</sub> = 13 A, V <sub>CC</sub> = 480 V V <sub>GE</sub> = 15 V, R <sub>G</sub> = 10 Ω Energy losses include "tail" and diode reverse recovery		-	47	-	ns	
Rise time	t <sub>r</sub>			-	30	-		
Turn-off delay time	t <sub>d(off)</sub>			-	250	-		
Fall time	t <sub>f</sub>			-	150	-		
Total switching loss	E <sub>ts</sub>			-	1.28	-		mJ
Internal emitter inductance	L <sub>E</sub>	Measured 5 mm from package		-	7.5	-	nH	
Input capacitance	C <sub>ies</sub>	V <sub>GE</sub> = 0 V		-	1600	-	pF	
Output capacitance	C <sub>oes</sub>	V <sub>CC</sub> = 30 V f = 1.0 MHz		-	130	-		
Reverse transfer capacitance	C <sub>res</sub>	See fig. 7		-	55	-		
Diode reverse recovery time	t <sub>rr</sub>	T <sub>J</sub> = 25 °C	See fig. 14	I <sub>F</sub> = 15 A V <sub>R</sub> = 200 V dI/dt = 200 A/μs	-	42	60	ns
		T <sub>J</sub> = 125 °C			-	74	120	
Diode peak reverse recovery charge	I <sub>rr</sub>	T <sub>J</sub> = 25 °C	See fig. 15		-	4.0	6.0	A
		T <sub>J</sub> = 125 °C			-	6.5	10	
Diode reverse recovery charge	Q <sub>rr</sub>	T <sub>J</sub> = 25 °C	See fig. 16		-	80	180	nC
		T <sub>J</sub> = 125 °C			-	220	600	
Diode peak rate of fall of recovery during t <sub>b</sub>	dl <sub>(rec)</sub> /dt	T <sub>J</sub> = 25 °C	See fig. 17		-	188	-	A/μs
		T <sub>J</sub> = 125 °C			-	160	-	

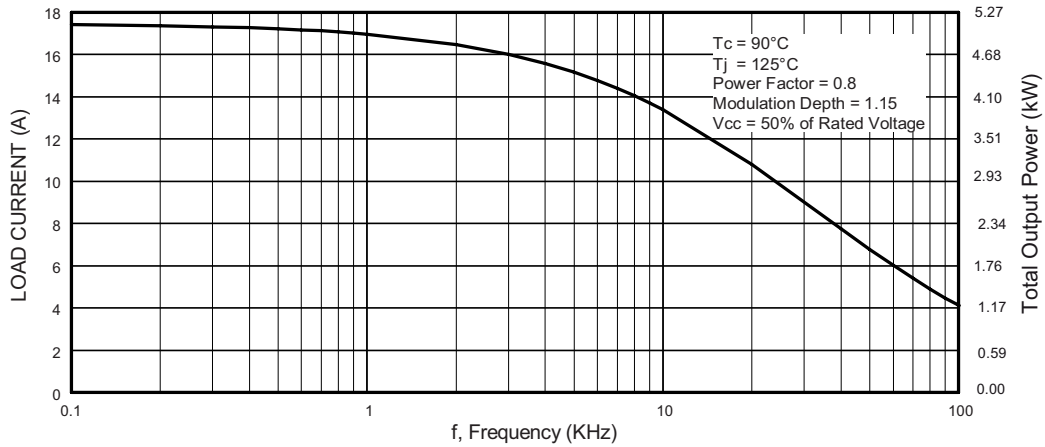


Fig. 1 - Typical Load Current vs. Frequency  
(Load Current =  $I_{RMS}$  of Fundamental)

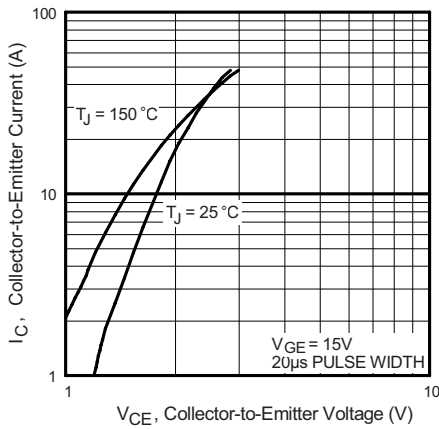


Fig. 2 - Typical Output Characteristics

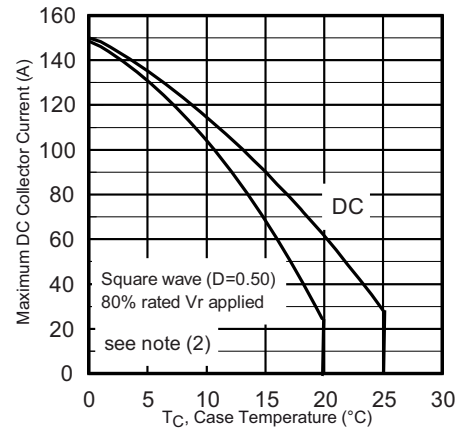


Fig. 4 - Maximum Collector Current vs. Case Temperature

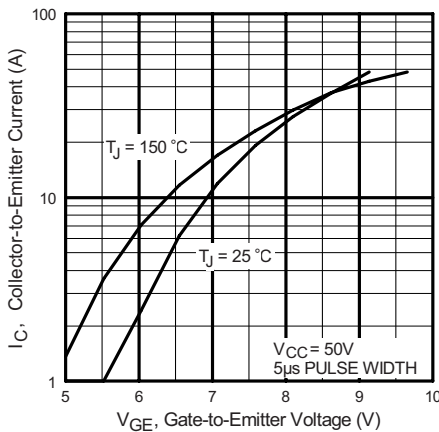


Fig. 3 - Typical Output Characteristics

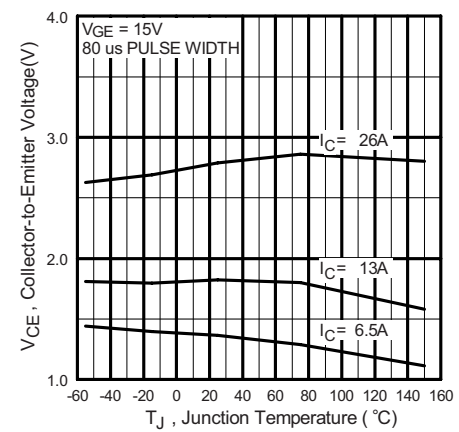


Fig. 5 - Typical Collector to Emitter Voltage vs. Junction Temperature

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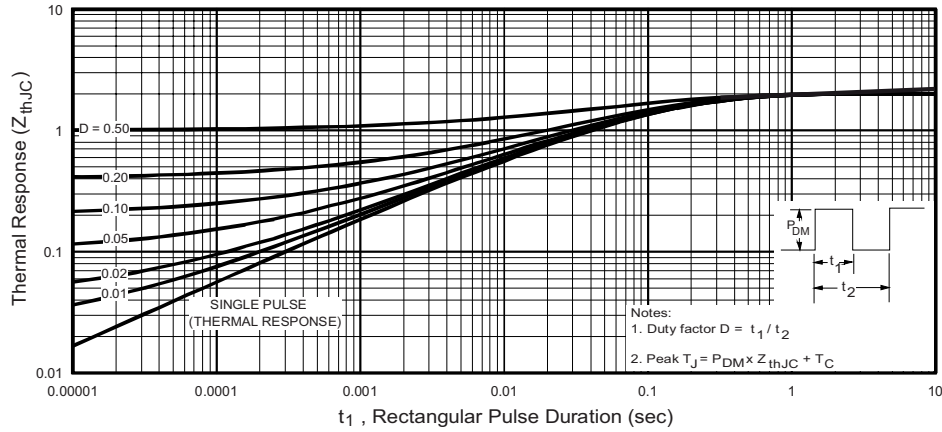


Fig. 6 - Maximum IGBT Effective Transient Thermal Impedance, Junction to Case

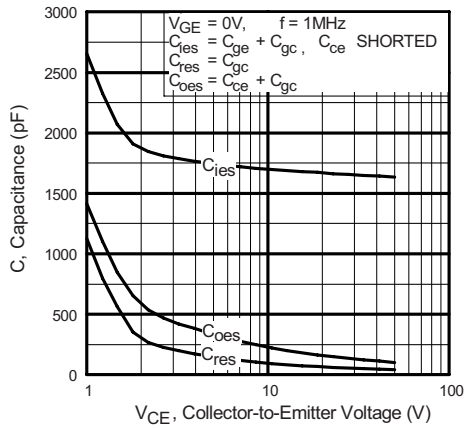


Fig. 7 - Typical Capacitance vs. Collector to Emitter Voltage

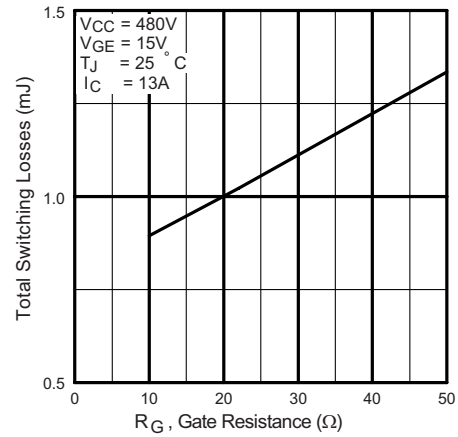


Fig. 9 - Typical Switching Losses vs. Gate Resistance

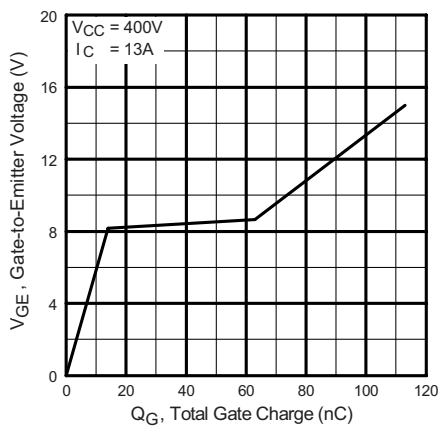


Fig. 8 - Typical Gate Charge vs. Gate to Emitter Voltage

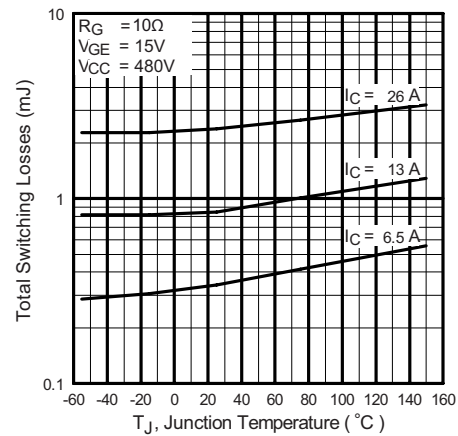


Fig. 10 - Typical Switching Losses vs. Junction Temperature

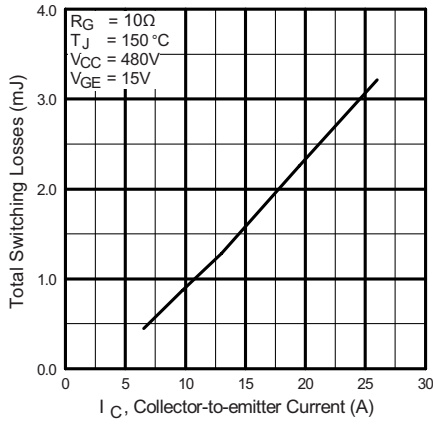


Fig. 11 - Typical Switching Losses vs. Collector to Emitter Current

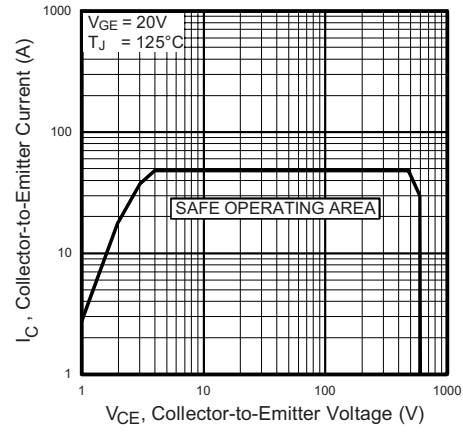


Fig. 12 - Turn-Off SOA

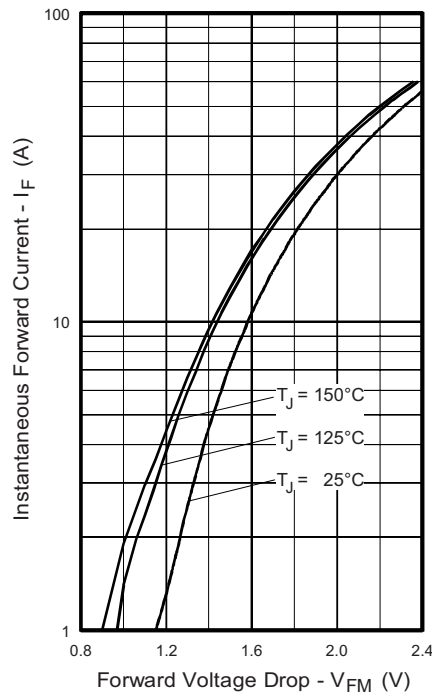


Fig. 13 - Maximum Forward Voltage Drop vs. Instantaneous Forward Current

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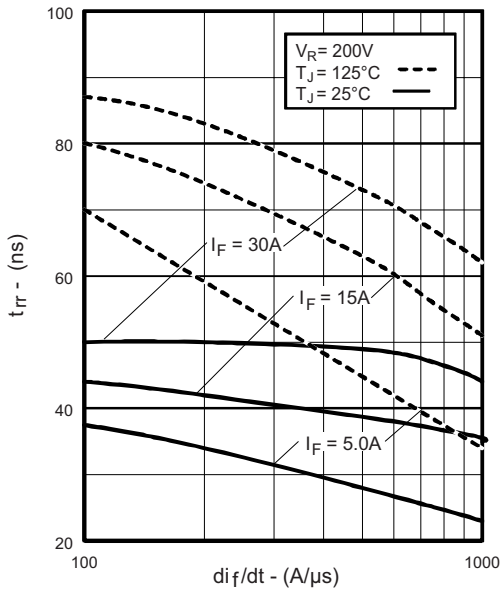


Fig. 14 - Typical Reverse Recovery Time vs.  $di_F/dt$

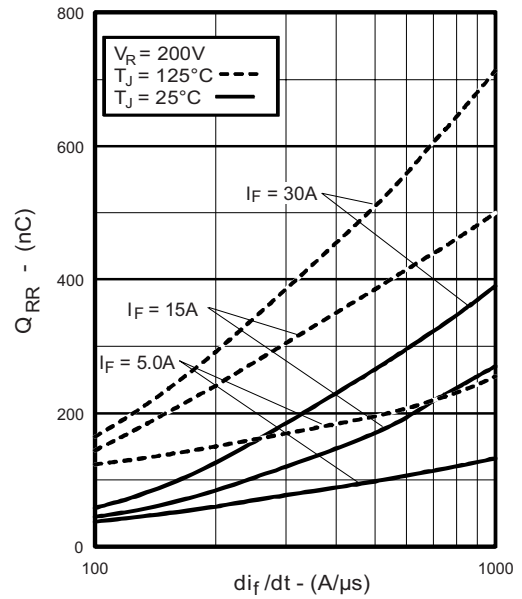


Fig. 16 - Typical Stored Charge vs.  $di_F/dt$

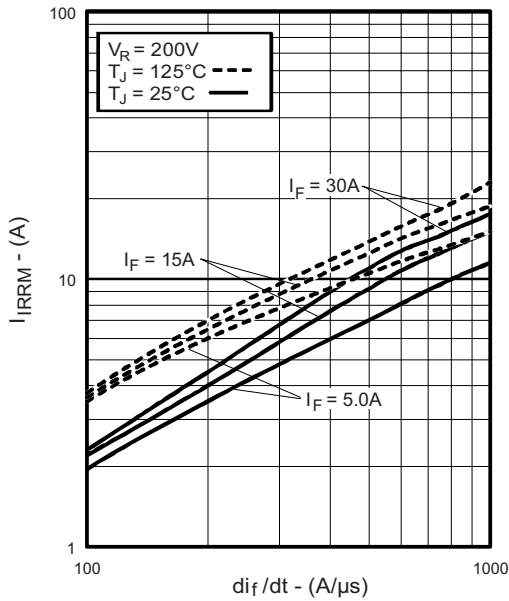


Fig. 15 - Typical Recovery Current vs.  $di_F/dt$

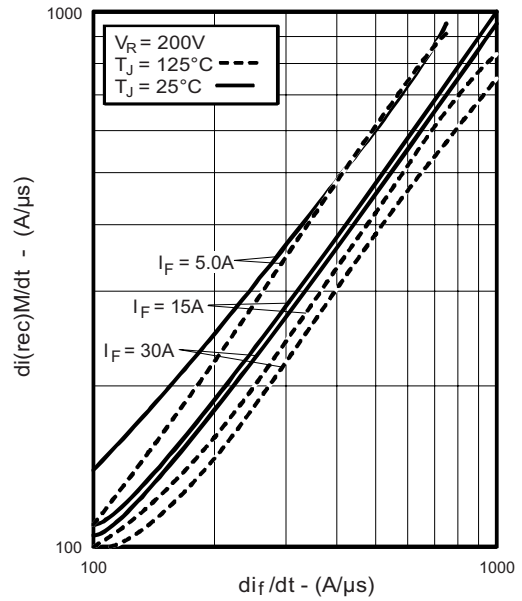


Fig. 17 - Typical  $dI_{(rec)M}/dt$  vs  $di_F/dt$

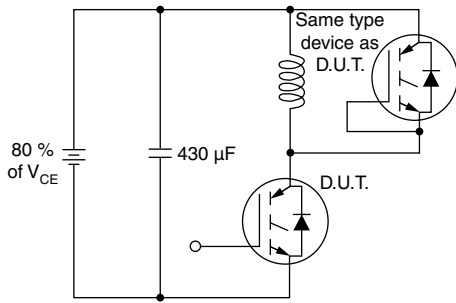


Fig. 18a - Test Circuit for Measurement of  $I_{LM}$ ,  $E_{on}$ ,  $E_{off(diode)}$ ,  $t_{rr}$ ,  $Q_{rr}$ ,  $I_{rr}$ ,  $t_{d(on)}$ ,  $t_r$ ,  $t_{d(off)}$ ,  $t_f$

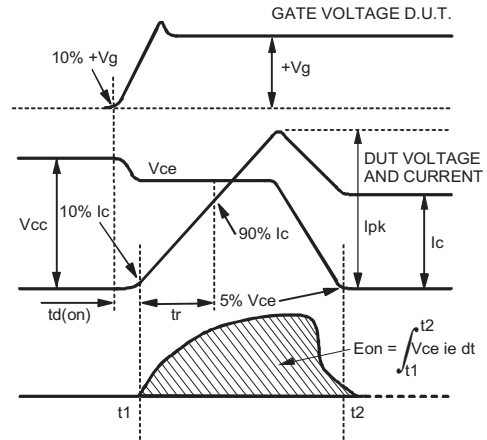


Fig. 18c - Test Waveforms for Circuit of Fig. 18a, Defining  $E_{on}$ ,  $t_{d(on)}$ ,  $t_r$

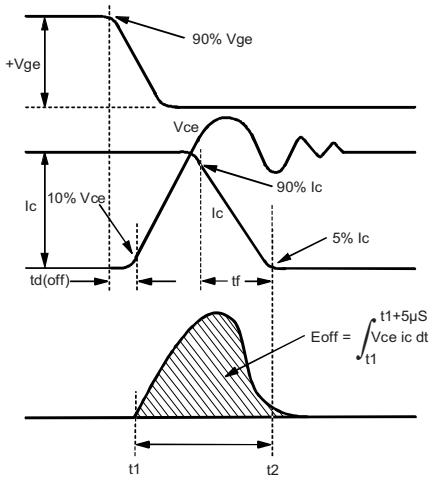


Fig. 18b - Test Waveforms for Circuit of Fig. 18a, Defining  $E_{off}$ ,  $t_{d(off)}$ ,  $t_f$

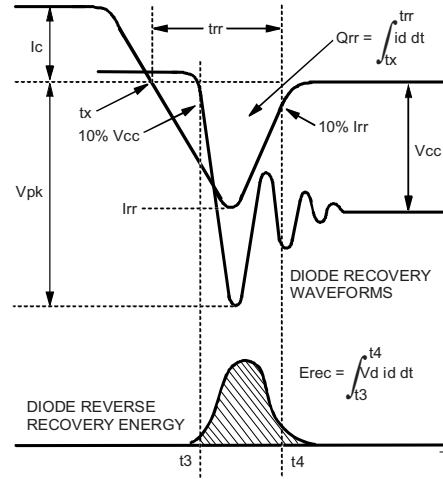


Fig. 18d - Test Waveforms for Circuit of Fig. 18a, Defining  $E_{rec}$ ,  $t_{rr}$ ,  $Q_{rr}$ ,  $I_{rr}$

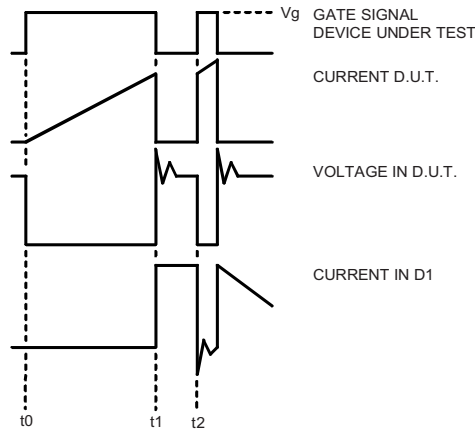


Fig. 18e - Macro Waveforms for Figure 18a's Test Circuit

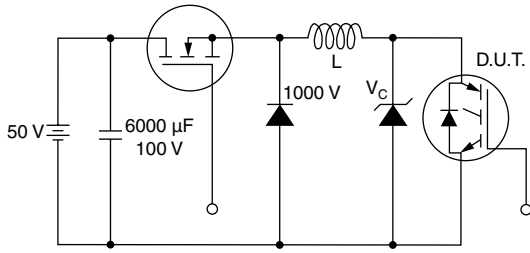


Fig. 19 - Clamped Inductive Load Test Circuit

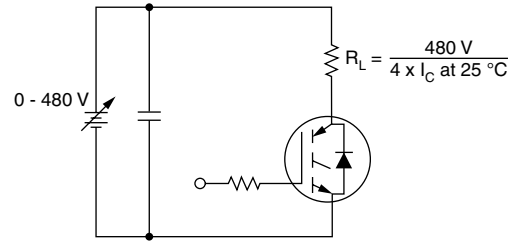
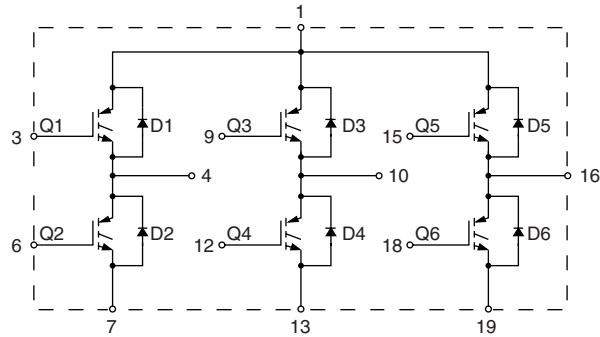


Fig. 20 - Pulsed Collector Current Test Circuit

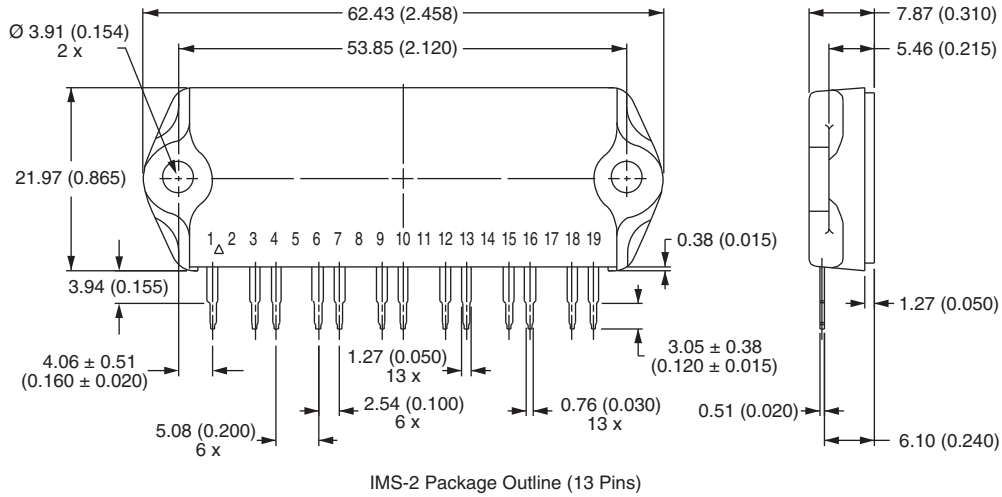
**CIRCUIT CONFIGURATION**



LINKS TO RELATED DOCUMENTS	
Dimensions	<a href="http://www.vishay.com/doc?95066">http://www.vishay.com/doc?95066</a>

## IMS-2 (SIP)

**DIMENSIONS** in millimeters (inches)



### Notes

- (1) Tolerance unless otherwise specified  $\pm 0.254$  mm (0.010")
- (2) Controlling dimension: inch
- (3) Terminal numbers are shown for reference only



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